

AM4934N-T1-PF-VB Datasheet Dual N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)	Q _g (Typ.)			
30	$0.008 \text{ at V}_{GS} = 10 \text{ V}$	8	15 nC			
30	$0.012 \text{ at V}_{GS} = 4.5 \text{ V}$	6.8	15110			

FEATURES

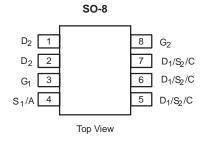
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- 100 % UIS Tested
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC



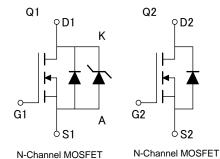
ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- Set Top Box
- Low Current DC/DC



Pin No.	Pin name			
1	DRAIN2			
2	DRAIN2			
3	GATE1			
4	SOURCE1/ANODE			
5	DRAIN1/SOURCE2/CATHODE			
6	DRAIN1/SOURCE2/CATHODE			
7	DRAIN1/SOURCE2/CATHODE			
8	GATE2			



ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted					
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V_{DS}	30	V	
Gate-Source Voltage		V_{GS}	± 20	V	
	T _C = 25 °C		8 ^a		
Continuous Drain Current (T _{.I} = 150 °C)	T _C = 70 °C	1	6.2		
Continuous Brain Current (1) = 100 °C)	T _A = 25 °C	- I _D	7.2 ^{b, c}		
	T _A = 70 °C		6.2 ^{b, c}	Α	
Pulsed Drain Current		I _{DM}	40		
Continuous Source-Drain Diode Current	T _C = 25 °C		2.25		
Continuous Source-Drain Diode Current	T _A = 25 °C		1.48 ^{b, c}		
Single Pulse Avalanche Current Single Pulse Avalanche Energy L = 0.1 mH		I _{AS}	5		
		E _{AS}	1.25	mJ	
	T _C = 25 °C	P _D	2.7		
Maximum Power Dissination	T _C = 70 °C		1.77	W	
Maximum Power Dissipation	T _A = 25 °C	1 ' D	1.78 ^{b, c}	VV	
	T _A = 70 °C		1.14 ^{b, c}		
Operating Junction and Storage Temperature	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{a, c, d}	t ≤ 10 s	R _{thJA}	58	70	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	38	45	C/VV	

Notes:

- a. Package limited, T_C = 25 °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s
- d. Maximum under Steady State conditions is 110 $^{\circ}\text{C/W}.$



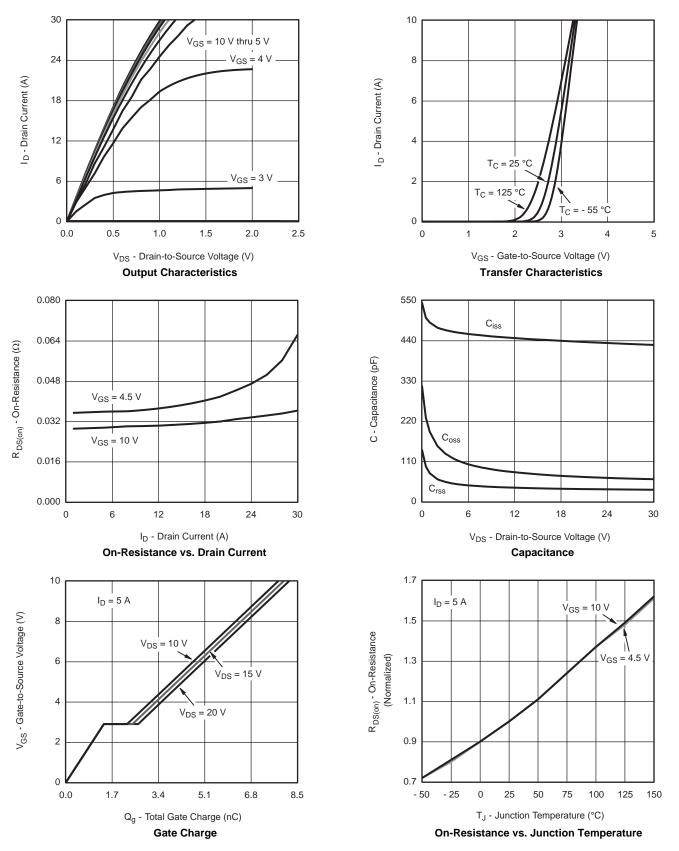
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static			•		l		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		32		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 5.0			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	1.0		2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
7 0	1 .	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C			10	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	10			Α	
		V _{GS} = 10 V, I _D = 5 A		0.008		Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 4 \text{ A}$		0.012			
Forward Transconductance ^a	g _{fs}	V _{DS} = 10 V, I _D = 5 A		16		S	
Dynamic ^b	<u> </u>	- -	<u> </u>		<u> </u>	1	
Input Capacitance	C _{iss}			586			
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		117		pF	
Reverse Transfer Capacitance	C _{rss}			55			
Total Gate Charge	Qg	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 5 \text{ A}$	5 V, V _{GS} = 10 V, I _D = 5 A	15		nC	
				3.7	5.6		
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 5 \text{ A}$		1.4			
Gate-Drain Charge	Q _{gd}			1.05			
Gate Resistance	R _g	f = 1 MHz	0.8	4.3	8.6	Ω	
Turn-On Delay Time	t _{d(on)}			12	24	ns	
Rise Time	t _r	V_{DD} = 15 V, R_L = 3 Ω		55	100		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 5$ A, V_{GEN} = 4.5 V, R_g = 1 Ω		11	22		
Fall Time	t _f			8	16		
Turn-On Delay Time	t _{d(on)}			4	8		
Rise Time	t _r	V_{DD} = 15 V, R_L = 3 Ω		9	18		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 5$ A, $V_{GEN} = 10$ V, $R_g = 1$ Ω		10	20		
Fall Time	t _f			6	12		
Drain-Source Body Diode Characteristi	cs		•				
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			2.25	Δ	
Pulse Diode Forward Current	I _{SM}				24	A	
Body Diode Voltage	V_{SD}	I _S = 2 A, V _{GS} = 0 V		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			11	20	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 5 A, dI/dt = 100 A/μs, T _J = 25 °C		4	8	nC	
Reverse Recovery Fall Time	t _a	$I_F = 3 \text{ A}$, $I_J = 25 \text{ C}$		7			
Reverse Recovery Rise Time	t _b	7		4		ns	

Notes

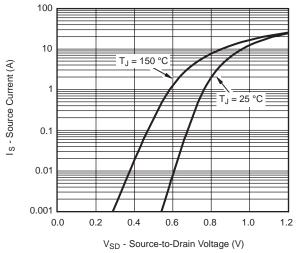
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

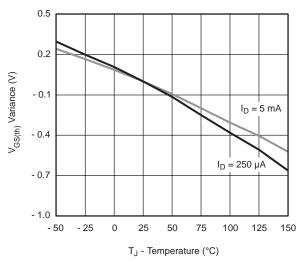




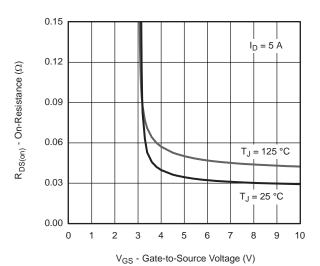




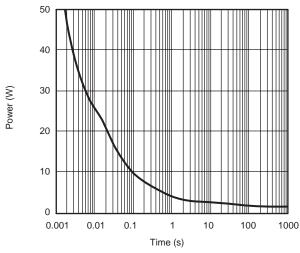
Source-Drain Diode Forward Voltage



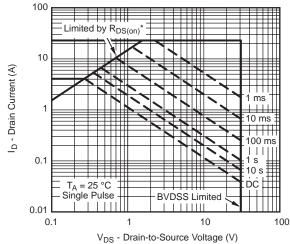
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



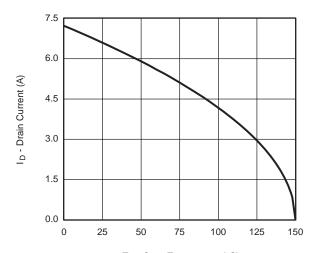
Single Pulse Power



* V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

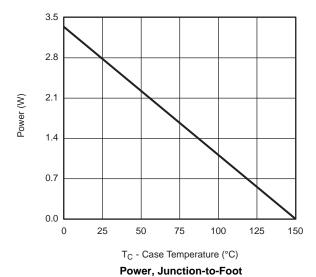
Safe Operating Area, Junction-to-Ambient

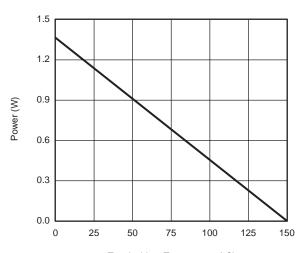




T_C - Case Temperature (°C)

Current Derating*



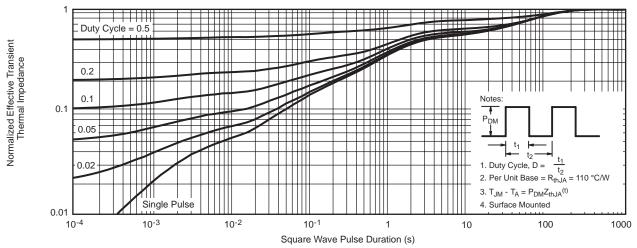


T_A - Ambient Temperature (°C)

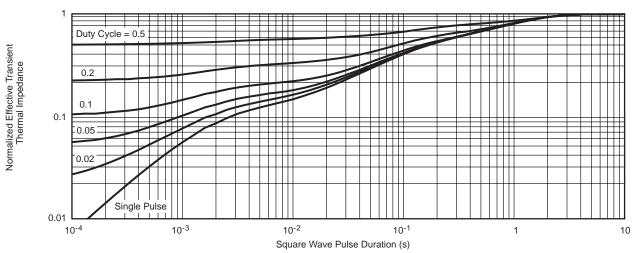
Power, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







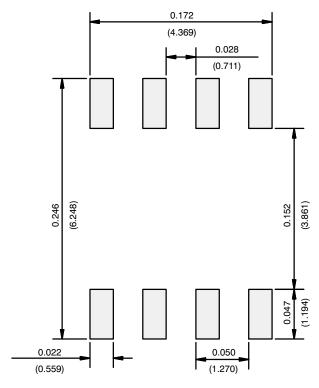
	MILLIM	IETERS	INCHES		
DIM	Min	Max	Min	Max	
Α	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
FCN: C-06527-Rev L 11-Sen-06					

ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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